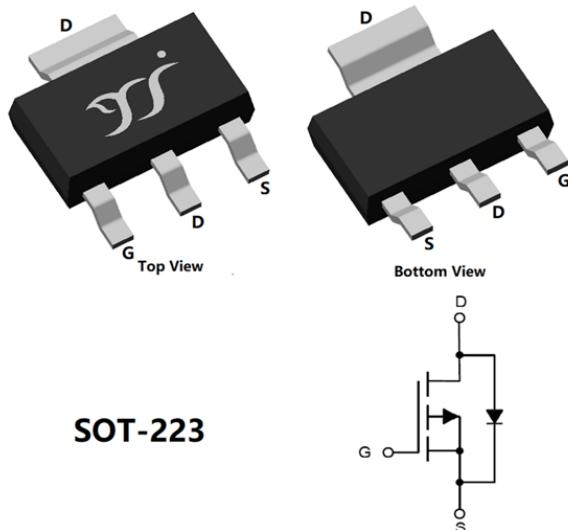




P-Channel Enhancement Mode Field Effect Transistor



Product Summary

• V_{DS}	-60V
• I_D	-3.6A
• $R_{DS(ON)}$ (at $V_{GS}=-10V$)	<72mΩ
• $R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	<90mΩ

General Description

- High density cell design for Low RDS(ON)
- High Speed switching
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- PWM applications
- Power management
- Load switch

■ Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit
Drain-source Voltage			V_{DS}	-	-60	V
Gate-source Voltage			V_{GS}	-20	20	
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=25^\circ C, V_{GS}=-10V$	I_D	-	-3.6	A
		$T_A=100^\circ C, V_{GS}=-10V$		-	-2.3	
Pulsed Drain Current	$T_A=25^\circ C, t_p \leq 10\mu s$		I_{DM}	-	-28.8	
Maximum Body-Diode Continuous Current	$T_A=25^\circ C$		I_S		-1.9	
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^\circ C$	P_D	-	1.7	W
		$T_A=100^\circ C$		-	0.7	
Junction and Storage Temperature Range			T_J, T_{STG}	-55	150	°C

■ Thermal Resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	-	71	°C/W

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJM072P06A	F2	M072P06A	2500	5000	25000	13" reel



■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A, T_j=25^\circ C$	-60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-60V, V_{GS}=0V, T_j=25^\circ C$	-	-	-1	μA
		$V_{DS}=-60V, V_{GS}=0V, T_j=150^\circ C$	-	-	-100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V, T_j=25^\circ C$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A, T_j=25^\circ C$	-1	-1.5	-2	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-2.7A, T_j=25^\circ C$	-	57	72	$m\Omega$
		$V_{GS}=-4.5V, I_D=-1.4A, T_j=25^\circ C$	-	66	90	$m\Omega$
Diode Forward Voltage	V_{SD}	$I_S=-1.9A, V_{GS}=0V, T_j=25^\circ C$	-	-0.80	-1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^\circ C$	-	5	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=-30V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	1190	-	pF
Output Capacitance	C_{oss}		-	63	-	
Reverse Transfer Capacitance	C_{rss}		-	56	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=-10V, V_{DS}=-30V, I_D=-2.7A, T_j=25^\circ C$	-	30	-	nC
Gate-Source Charge	Q_{gs}		-	2	-	
Gate-Drain Charge	Q_{gd}		-	4	-	
Reverse Recovery Charge	Q_{rr}	$I_F=-2.7A, di/dt=100A/\mu s, V_{GS}=0V, V_R=-15V, T_j=25^\circ C$	-	22	-	nC
Reverse Recovery Time	t_{rr}		-	20	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-30V, I_D=-2.7A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	7.4	-	ns
Turn-on Rise Time	t_r		-	3.5	-	
Turn-off Delay Time	$t_{D(off)}$		-	43.3	-	
Turn-off Fall Time	t_f		-	15.4	-	

Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of R_{QJA} is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

■Typical Electrical and Thermal Characteristics Diagrams

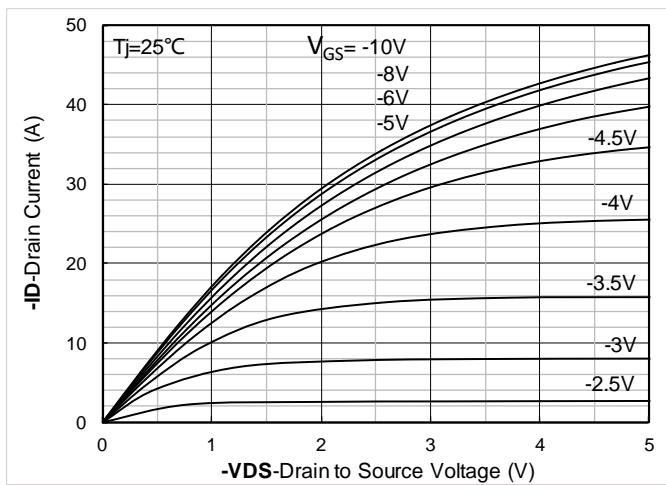


Figure 1. Output Characteristics; typical values

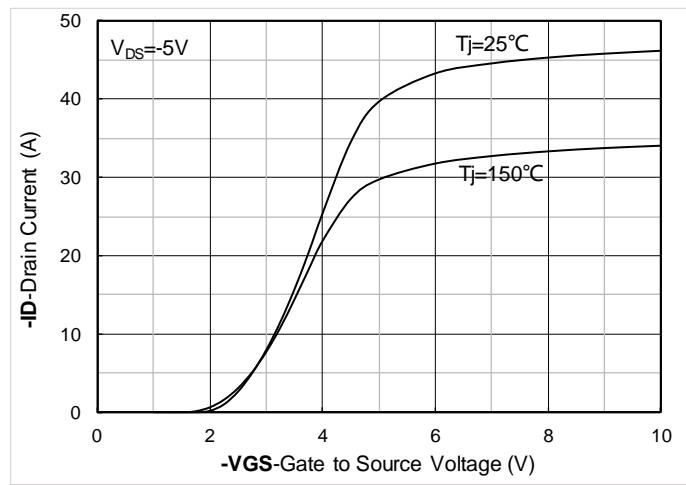


Figure 2. Transfer Characteristics; typical values

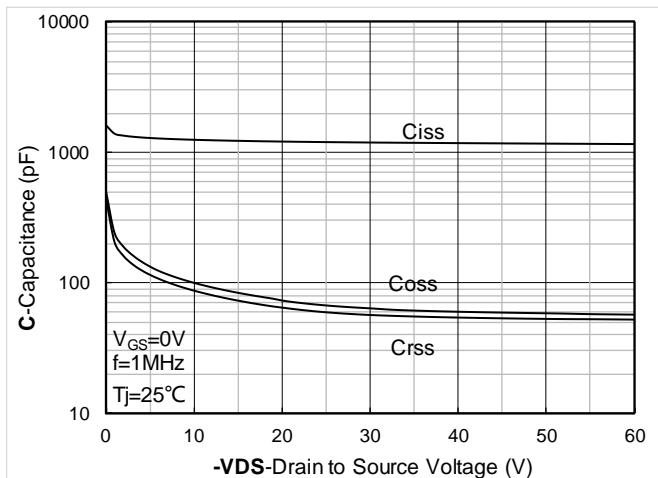


Figure 3. Capacitance Characteristics; typical values

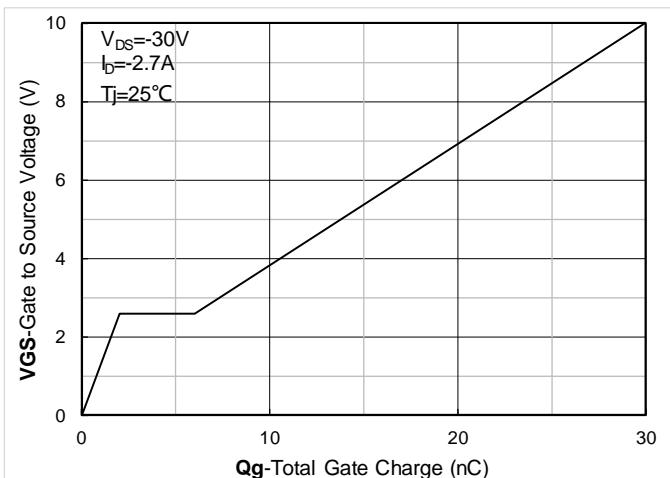


Figure 4. Gate Charge; typical values

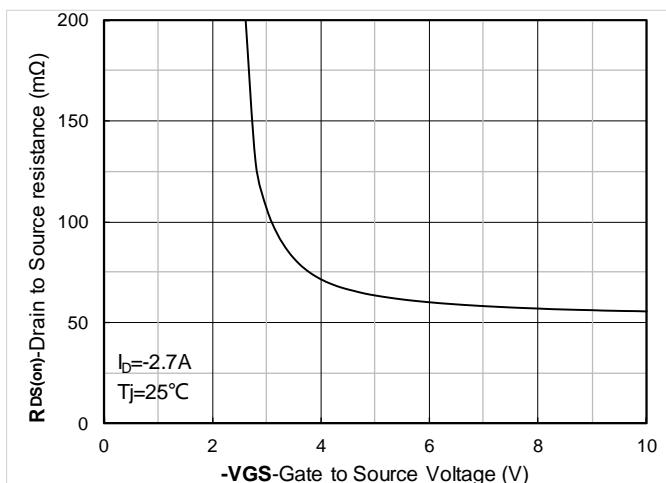


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

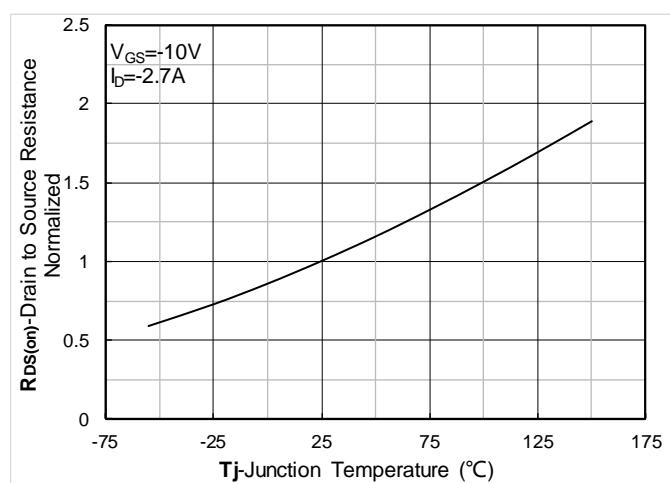


Figure 6. Normalized On-Resistance

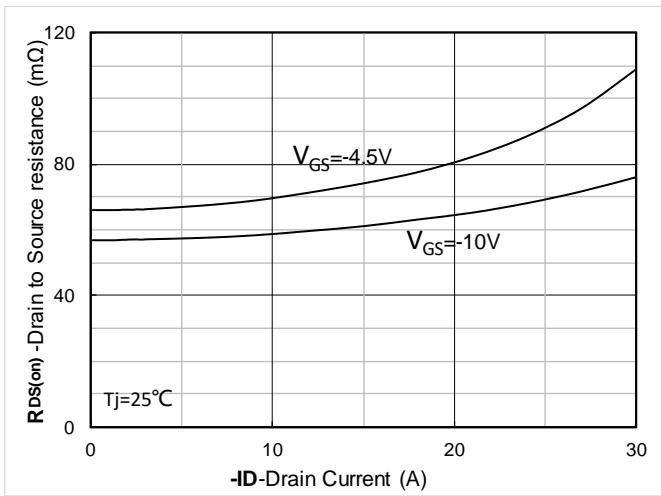


Figure 7. RDS(on) vs. Drain Current; typical values

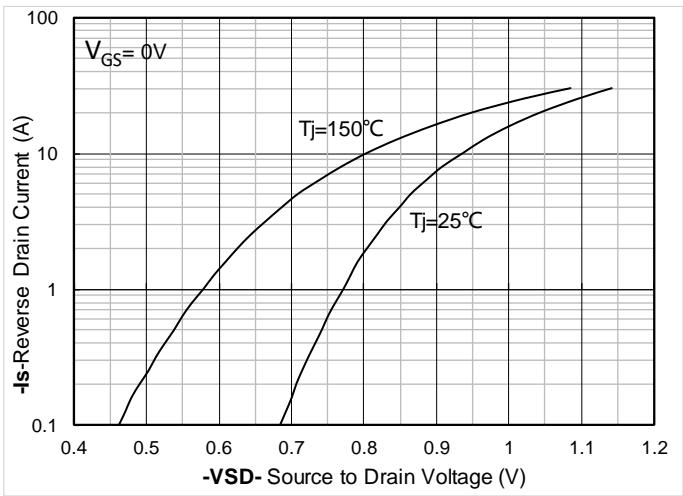


Figure 8. Forward characteristics of reverse diode; typical values

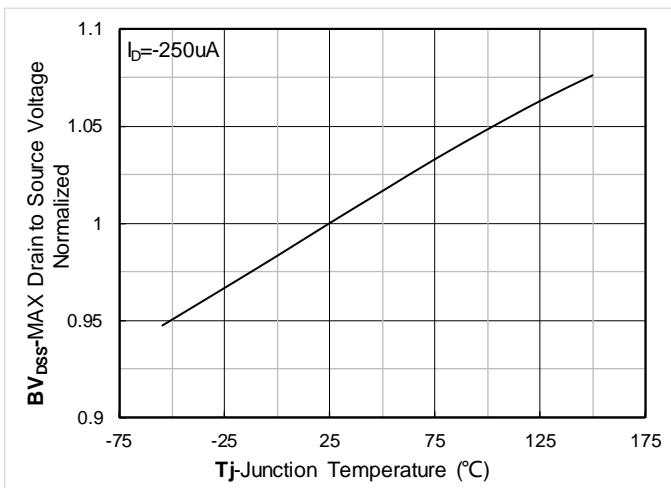


Figure 9. Normalized breakdown voltage

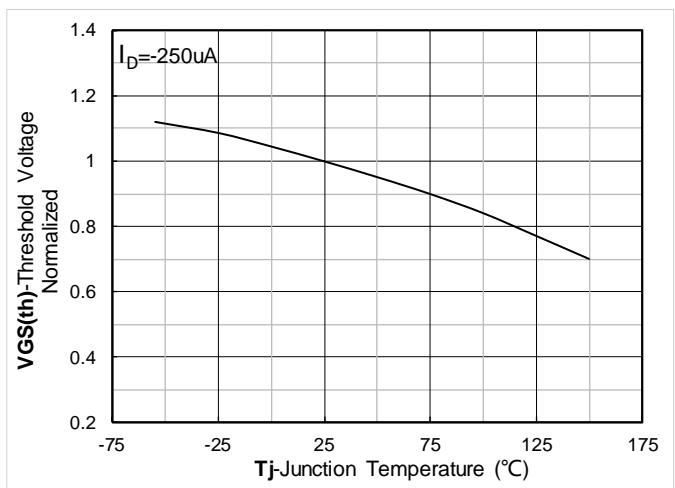


Figure 10. Normalized Threshold voltage

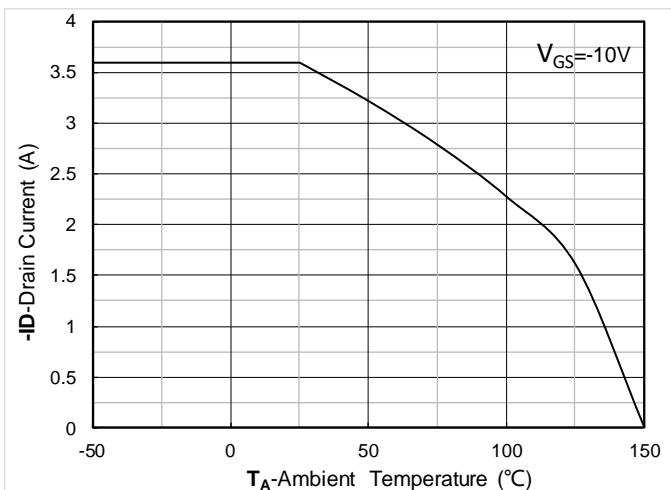


Figure 11. Current dissipation

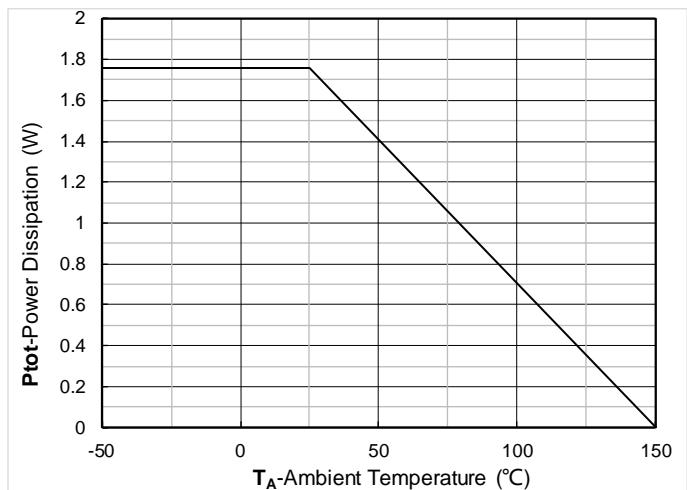


Figure 12. Power dissipation

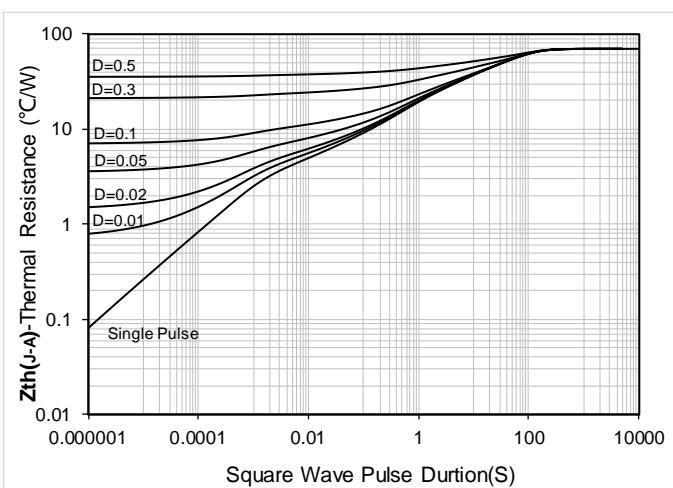


Figure 13. Maximum Transient Thermal Impedance

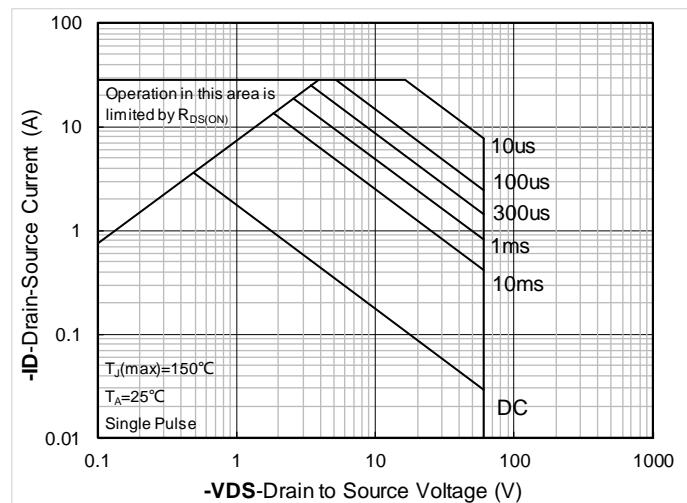
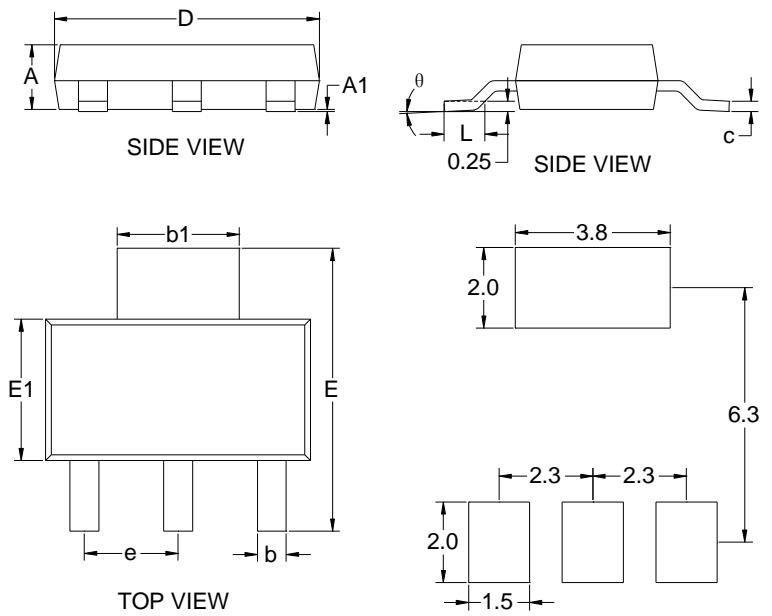


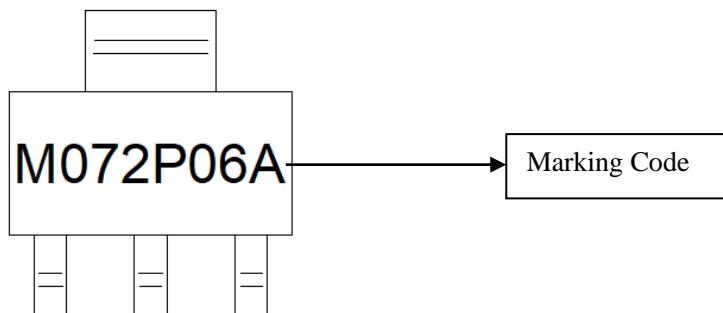
Figure 14. Safe Operation Area

**■ SOT-223 Package Information**

DIM	DIMENSIONS			
	INCHES		MM	
	MIN	MAX	MN	MAX
A	0.0591	0.0670	1.5000	1.7000
A1	0.0008	0.0039	0.0200	0.1000
b	0.0259	0.0330	0.6600	0.8400
b1	0.1140	0.1220	2.9000	3.1000
c	0.0090	0.0138	0.2300	0.3500
D	0.2480	0.2640	6.3000	6.7000
E	0.2637	0.2874	6.7000	7.3000
E1	0.1290	0.1460	3.3000	3.7000
e	0.0866	0.0945	2.2000	2.4000
L	0.0295	0.0492	0.7500	1.2500
θ	0°	10°	0°	10°



■Marking



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. M072P06A is marking code.
4. Body color: Black



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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use or sale.

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